

**DMN3200U** 

#### N-CHANNEL ENHANCEMENT MODE FIELD EFFECT TRANSISTOR

### **Features**

- Low On-Resistance
  - $90m\Omega @ V_{GS} = 4.5V$
  - $110m\Omega$  @  $V_{GS} = 2.5V$
  - 200mΩ @ V<sub>GS</sub> = 1.5V
- Low Gate Threshold Voltage
- Low Input Capacitance
- ESD Protected Gate
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

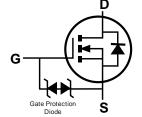
## **Mechanical Data**

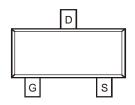
- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.008 grams (Approximate)

SOT23









Top View

**Equivalent Circuit** 

Top View

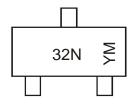
## **Ordering Information** (Note 4)

Part Number	Case	Packaging
DMN3200U-7	SOT23	3,000/Tape & Reel

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**



32N = Marking Code YM = Date Code Marking Y or  $\overline{Y}$  = Year (ex: D = 2016) M = Month (ex: 9 = September)

Date Code Key

Year	2007	~		2016	2017	201	8	2019	2020	20:	21	2022
Code	U	2		D	Е	F		G	Н	I		J
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

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# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Drain-Source Voltage	V <sub>DSS</sub>	30	V
Gate-Source Voltage	V <sub>GSS</sub>	±8	V
Drain Current (Note 5)	I <sub>D</sub>	2.2	А
Pulsed Drain Current (Note 5)	I <sub>DM</sub>	9	А

# Thermal Characteristics ( $@T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	$P_D$	650	mW
Thermal Resistance, Junction to Ambient	$R_{ heta JA}$	192	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

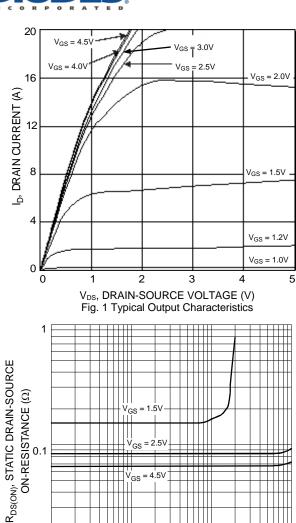
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

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Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 6)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>			1	μΑ	$V_{DS} = 30V$ , $V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>			±5	μΑ	$V_{GS} = \pm 8V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 6)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	0.45		1.0	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
			62	90 110 200	mΩ	$V_{GS} = 4.5V, I_D = 2.2A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	70 150			$V_{GS} = 2.5V, I_D = 2A$	
						V <sub>GS</sub> = 1.5V, I <sub>D</sub> = 0.67A	
Forward Transfer Admittance	Y <sub>fs</sub>		5		S	V <sub>DS</sub> = 5V, I <sub>D</sub> = 2.2A	
Diode Forward Voltage (Note 6)	V <sub>SD</sub>			0.9	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	C <sub>iss</sub>		290		pF		
Output Capacitance	Coss		66		pF	$V_{DS} = 10V, V_{GS} = 0V$ f = 1.0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>		35		pF	7 - 1.01/11/2	
Turn-On Delay Time	t <sub>D(ON)</sub>		40.2		ns	$V_{DD} = 10V, I_D = 2A, V_{GEN} = 4.5V,$ $R_L = 5\Omega, R_{GEN} = 6\Omega$	
Turn-On Rise Time	t <sub>R</sub>	_	43.1	_	ns		
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	471	_	ns		
Turn-Off Fall Time	t <sub>F</sub>	_	104		ns		

Notes:

- 5. Device mounted on FR-4 PCB, on minimum recommended pad layout on 2oz. Copper pads.
- 6. Short duration pulse test used to minimize self-heating effect.
- 7. Guaranteed by design. Not subject to product testing.





 $I_D$ , DRAIN-SOURCE CURRENT (A) Fig. 3 On-Resistance vs. Drain Current & Gate Voltage

0.1

0.01 0.01

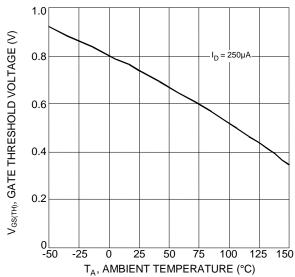


Fig. 5 Gate Threshold Variation vs. Ambient Temperature

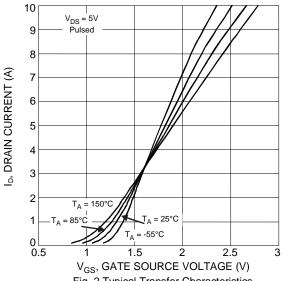


Fig. 2 Typical Transfer Characteristics

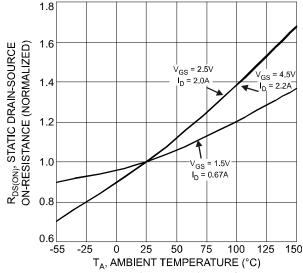
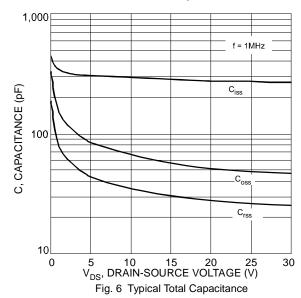
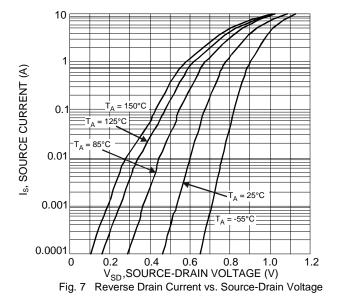


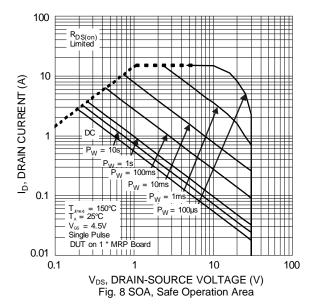
Fig. 4 Normalized Static Drain-Source On-Resistance vs. Ambient Temperature



May 2016







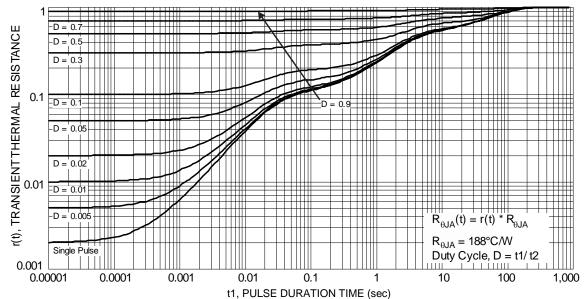
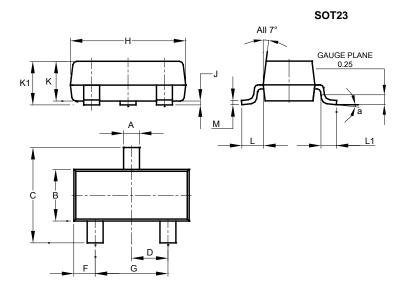


Fig. 9 Transient Thermal Resistance



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

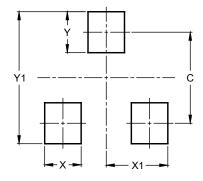


SOT23							
Dim	Min	Max	Тур				
Α	0.37	0.51	0.40				
В	1.20	1.40	1.30				
С	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Н	2.80	3.00	2.90				
J	0.013	0.10	0.05				
K	0.890	1.00	0.975				
K1	0.903	1.10	1.025				
L	0.45	0.61	0.55				
L1	0.25	0.55	0.40				
M	0.085	0.150	0.110				
а	0°	8°					
All Dimensions in mm							

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### SOT23



Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Y	0.9
Y1	2.9



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